

**FEATURES:**

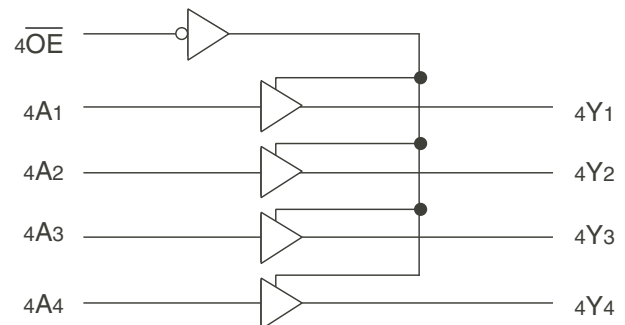
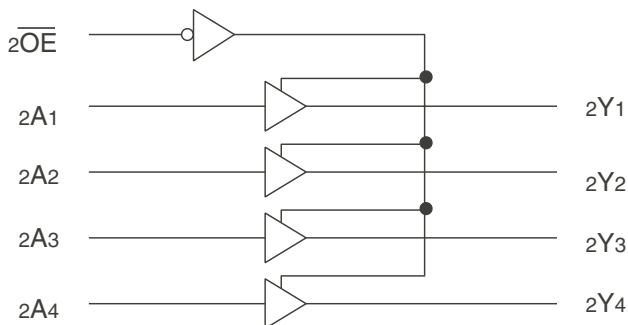
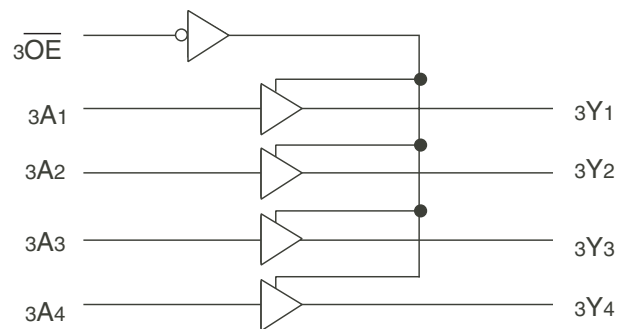
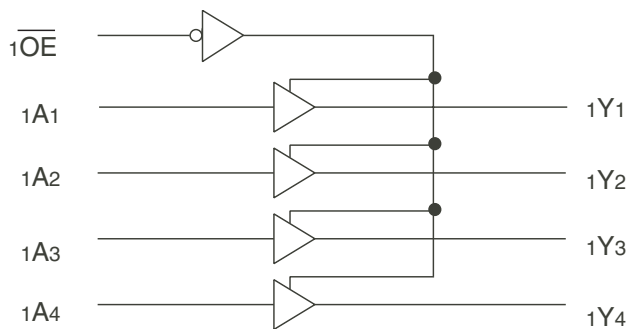
- 0.5 MICRON CMOS Technology
- High-speed, low-power CMOS replacement for ABT functions
- Typical  $t_{sk(o)}$  (Output Skew) < 250ps
- Low input and output leakage  $\leq 1\mu A$  (max.)
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- High drive outputs (-32mA  $I_{OH}$ , 64mA  $I_{OL}$ )
- Power off disable outputs permit "live insertion"
- Typical  $V_{OLP}$  (Output Ground Bounce) < 1.0V at  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$
- Available in the following packages:
  - Industrial: SSOP, TSSOP
  - Military: CERPACK

**DESCRIPTION:**

The FCT16244T 16-Bit Buffer/Line Driver is for bus interface or signal buffering applications requiring high speed and low power dissipation. These devices have a flow through pin organization, and shrink packaging to simplify board layout. All inputs are designed with hysteresis for improved noise margin. The three-state controls allow independent 4-bit, 8-bit or combined 16-bit operation. These parts are plug in replacements for 54/74ABT16244 where higher speed, lower noise or lower power dissipation levels are desired.

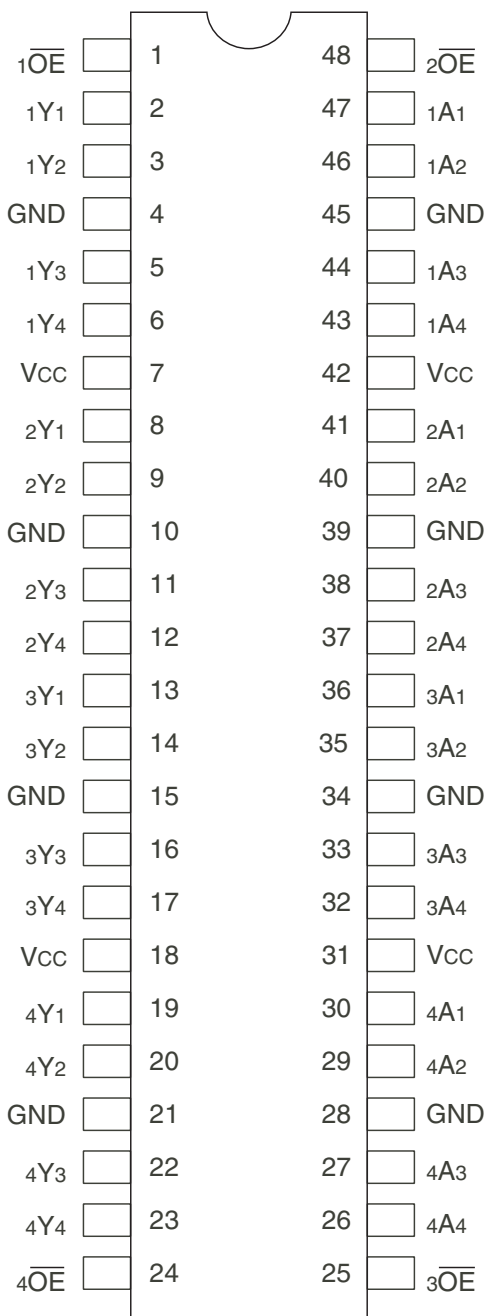
The FCT16244T is ideally suited for driving high capacitance loads (>200pF) and low impedance backplanes. These "high drive" buffers are designed with power off disable capability to allow "live insertion" of boards when used in a backplane interface.

**FUNCTIONAL BLOCK DIAGRAM**



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## PIN CONFIGURATION



SSOP/ TSSOP/ CERPACK  
TOP VIEW

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Description	Max	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM <sup>(3)</sup>	Terminal Voltage with Respect to GND	-0.5 to V <sub>CC</sub> +0.5	V
TSTG	Storage Temperature	-65 to +150	°C
I <sub>OUT</sub>	DC Output Current	-60 to +120	mA

### NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- All device terminals except FCT162XXXT Output and I/O terminals.
- Output and I/O terminals terminals for FCT162XXXT and FCT166XXXT.

## CAPACITANCE (T<sub>A</sub> = +25°C, F = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Typ.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	3.5	6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	3.5	8	pF

### NOTE:

- This parameter is measured at characterization but not tested.

## PIN DESCRIPTION

Pin Names	Description
x $\overline{OE}$	3-State Output Enable Inputs (Active LOW)
xAX	Data Inputs
xYx	3-State Outputs

## FUNCTION TABLE<sup>(1)</sup>

Inputs		Outputs
x $\overline{OE}$	xAX	xYx
L	L	L
L	H	H
H	X	Z

### NOTE:

- H = HIGH Voltage Level  
X = Don't Care  
L = LOW Voltage Level  
Z = High-Impedance

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial:  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{CC} = 5.0\text{V} \pm 10\%$ ; Military:  $T_A = -55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ,  $V_{CC} = 5.0\text{V} \pm 10\%$

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit
$V_{IH}$	Input HIGH Level	Guaranteed Logic HIGH Level	2	—	—	V
$V_{IL}$	Input LOW Level	Guaranteed Logic LOW Level	—	—	0.8	V
$I_{IH}$	Input HIGH Current (Input pins) <sup>(5)</sup>	$V_{CC} = \text{Max.}$ $V_I = V_{CC}$	—	—	$\pm 1$	$\mu\text{A}$
	Input HIGH Current (I/O pins) <sup>(5)</sup>		—	—	$\pm 1$	
$I_{IL}$	Input LOW Current (Input pins) <sup>(5)</sup>	$V_I = \text{GND}$	—	—	$\pm 1$	$\mu\text{A}$
	Input LOW Current (I/O pins) <sup>(5)</sup>		—	—	$\pm 1$	
$I_{OZH}$	High Impedance Output Current (3-State Output pins) <sup>(5)</sup>	$V_{CC} = \text{Max.}$ $V_O = 2.7\text{V}$	—	—	$\pm 1$	$\mu\text{A}$
$I_{OZL}$			$V_O = 0.5\text{V}$	—	—	
$V_{IK}$	Clamp Diode Voltage	$V_{CC} = \text{Min.}, I_{IN} = -18\text{mA}$	—	-0.7	-1.2	V
$I_{OS}$	Short Circuit Current	$V_{CC} = \text{Max.}, V_O = \text{GND}^{(3)}$	-80	-140	-250	mA
$V_H$	Input Hysteresis	—	—	100	—	mV
$I_{CCL}$ $I_{CCH}$ $I_{CCZ}$	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$ $V_{IN} = \text{GND or } V_{CC}$	—	5	500	$\mu\text{A}$

## OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit	
$I_O$	Output Drive Current	$V_{CC} = \text{Max.}, V_O = 2.5\text{V}^{(3)}$	-50	—	-180	mA	
$V_{OH}$	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -3\text{mA}$ ,	2.5	3.5	—	V
			$I_{OH} = -12\text{mA MIL}$	2.4	3.5	—	V
			$I_{OH} = -15\text{mA IND}$	—	—	—	—
			$I_{OH} = -24\text{mA MIL}$ $I_{OH} = -32\text{mA IND}^{(4)}$	2	3	—	V
$V_{OL}$	Output LOW Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	—	0.2	0.55	V	
$I_{OFF}$	Input/Output Power Off Leakage <sup>(5)</sup>	$V_{CC} = 0\text{V}, V_{IN} \text{ or } V_O \leq 4.5\text{V}$	—	—	$\pm 1$	$\mu\text{A}$	

### NOTES:

- For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at  $V_{CC} = 5.0\text{V}$ ,  $+25^{\circ}\text{C}$  ambient.
- Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- Duration of the condition can not exceed one second.
- The test limit for this parameter is  $\pm 5\mu\text{A}$  at  $T_A = -55^{\circ}\text{C}$ .

## POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Unit
$\Delta I_{CC}$	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}$ $V_{IN} = 3.4V^{(3)}$		—	0.5	1.5	mA
$I_{CCD}$	Dynamic Power Supply Current <sup>(4)</sup>	$V_{CC} = \text{Max.}$ Outputs Open $\overline{xOE} = \text{GND}$ One Input Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	60	100	$\mu\text{A}/\text{MHz}$
$I_C$	Total Power Supply Current <sup>(6)</sup>	$V_{CC} = \text{Max.}$ Outputs Open $f_i = 10\text{MHz}$ 50% Duty Cycle $\overline{xOE} = \text{GND}$ One Bit Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	0.6	1.5	mA
			$V_{IN} = 3.4V$ $V_{IN} = \text{GND}$	—	0.9	2.3	
		$V_{CC} = \text{Max.}$ Outputs Open $f_i = 2.5\text{MHz}$ 50% Duty Cycle $\overline{xOE} = \text{GND}$ Sixteen Bits Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	2.4	4.5 <sup>(5)</sup>	
			$V_{IN} = 3.4V$ $V_{IN} = \text{GND}$	—	6.4	16.5 <sup>(5)</sup>	

### NOTES:

- For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at  $V_{CC} = 5.0V$ ,  $+25^\circ\text{C}$  ambient.
- Per TTL driven input ( $V_{IN} = 3.4V$ ). All other inputs at  $V_{CC}$  or  $\text{GND}$ .
- This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- Values for these conditions are examples of the  $I_{CC}$  formula. These limits are guaranteed but not tested.
- $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$   
 $I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP} / 2 + f_i N_i)$   
 $I_{CC} = \text{Quiescent Current } (I_{CC1}, I_{CC2} \text{ and } I_{CC3})$   
 $\Delta I_{CC} = \text{Power Supply Current for a TTL High Input } (V_{IN} = 3.4V)$   
 $D_H = \text{Duty Cycle for TTL Inputs High}$   
 $N_T = \text{Number of TTL Inputs at } D_H$   
 $I_{CCD} = \text{Dynamic Current caused by an Input Transition Pair (HLH or LHL)}$   
 $f_{CP} = \text{Clock Frequency for Register Devices (Zero for Non-Register Devices)}$   
 $N_{CP} = \text{Number of Clock Inputs at } f_{CP}$   
 $f_i = \text{Input Frequency}$   
 $N_i = \text{Number of Inputs at } f_i$

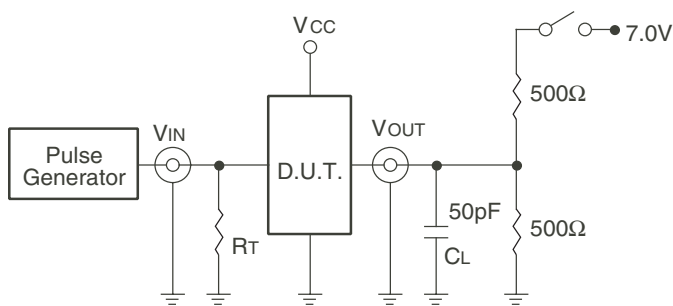
## SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition <sup>(1)</sup>	54FCT16244T		54/74FCT16244AT				54/74FCT16224CT				Unit
			Mil.		Ind.		Mil.		Ind.		Mil.		
			Min. <sup>(2)</sup>	Max.	Min. <sup>(2)</sup>	Max.	Min. <sup>(2)</sup>	Max.	Min. <sup>(2)</sup>	Max.	Min. <sup>(2)</sup>	Max.	
$t_{PLH}$	Propagation Delay	$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.5	7	1.5	4.8	1.5	5.1	1.5	3.4	1.5	4.6	ns
$t_{PHL}$	$xAx$ to $xYx$												
$t_{PZH}$	Output Enable Time		1.5	8.5	1.5	6.2	1.5	6.5	1.5	4.4	1.5	6.5	
$t_{PZL}$													
$t_{PHZ}$	Output Disable Time		1.5	7.5	1.5	5.6	1.5	5.9	1.5	3.9	1.5	5.7	
$t_{PLZ}$													
$t_{SK(o)}$	Output Skew <sup>(3)</sup>		—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns

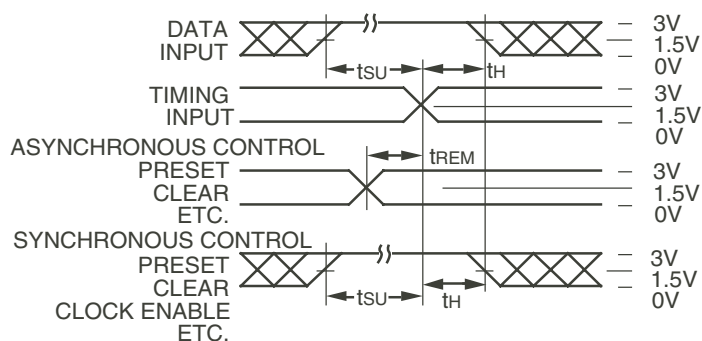
### NOTES:

- See test circuit and waveforms.
- Minimum limits are guaranteed but not tested on Propagation Delays.
- Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

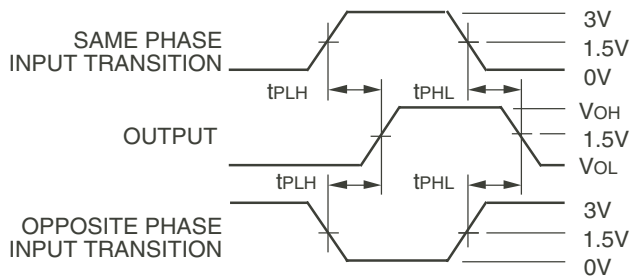
## TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



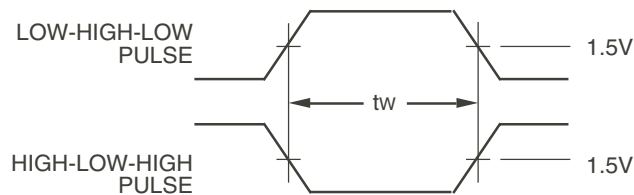
Propagation Delay

## SWITCH POSITION

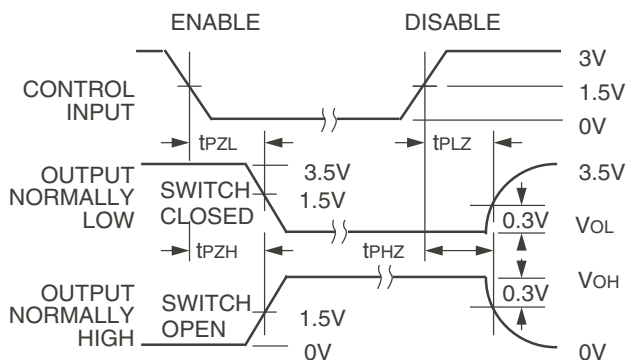
Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

### DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.  
RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



Pulse Width

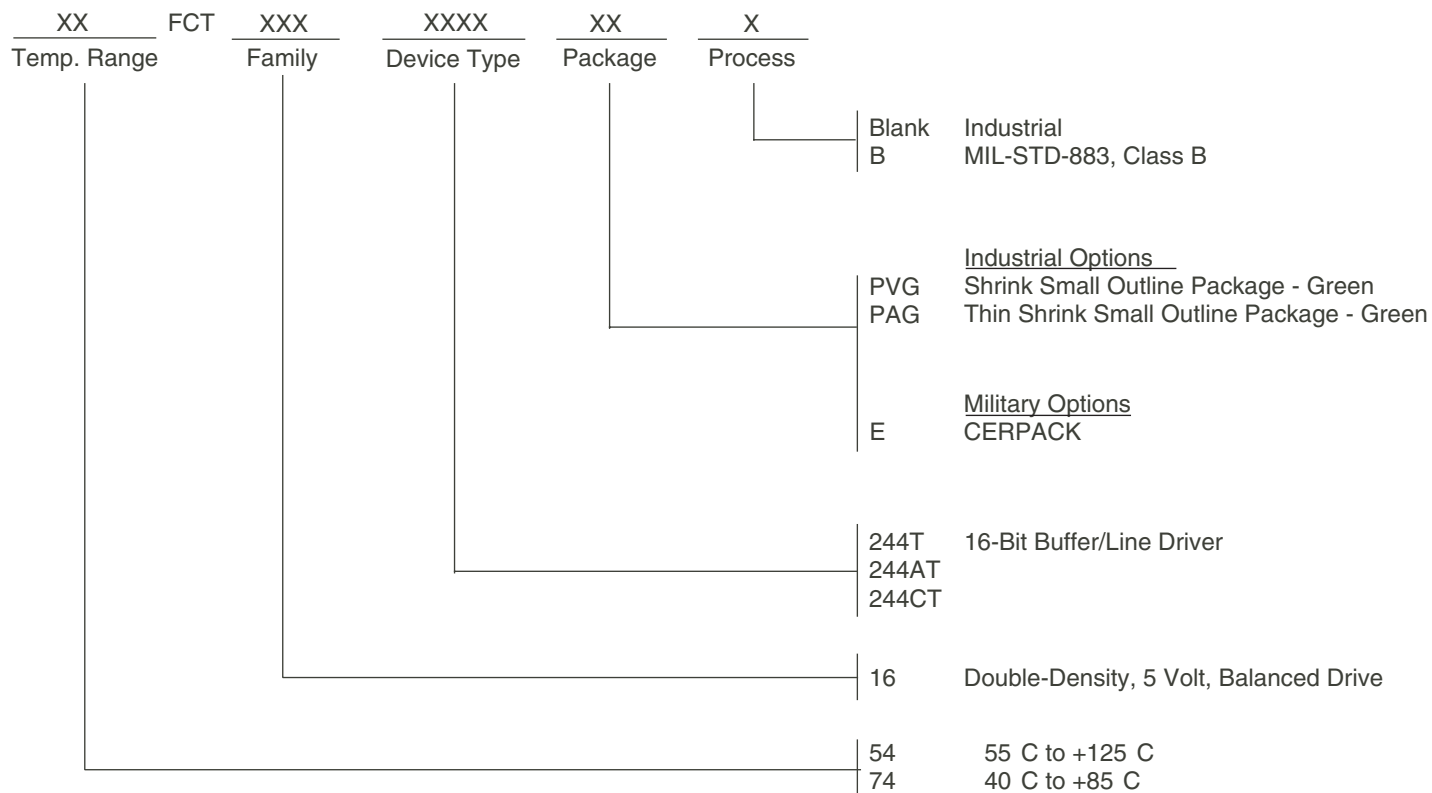


Enable and Disable Times

### NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- Pulse Generator for All Pulses: Rate  $\leq$  1.0MHz;  $t_f \leq$  2.5ns;  $t_r \leq$  2.5ns.

## ORDERING INFORMATION



## Datasheet Document History

09/06/09 Pg.6 Updated the ordering information by removing the "IDT" notation and non RoHS part.

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